

Product data sheet

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P-Channel Enhancement Mode Power MOSFET

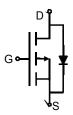
General Features

 $V_{DS} = -30V, I_D = -4.1A$ $R_{DS(ON)} < 95m\Omega @ V_{GS} = -4.5V$ $R_{DS(ON)} < 65m\Omega @ V_{GS} = -10V$

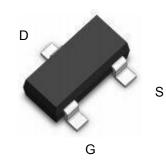
High power and current handing capability Lead free product is acquired Surface mount package

Application

PWM applications Load switch Power management



Schematic diagram



Absolute Maximum Ratings (T_A=25°Cunless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	-30	V
Gate-Source Voltage	V _{GS}	±20	V
Drain Current-Continuous	ID	-4.1	A
Drain Current-Pulsed (Note 1)	I _{DM}	-20	A
Maximum Power Dissipation	PD	1.4	W
Operating Junction and Storage Temperature Range	T _J ,T _{STG}	-55 To 150	°C

Thermal Characteristic

Thermal Resistance, Junction-to-Ambient (Note 2)	Reja	90	°C/W
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Electrical Characteristics (T_A=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =-250µA	-30	-33	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =-24V,V _{GS} =0V	-	-	-1	μA



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Parameter	Symbol	Condition	Min	Тур	Max	Unit
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)	I			,		
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =-250µA	-1	-1.5	-3	V
Drain October Drainteau		V _{GS} =-10V, I _D =-4.1A	-	48	65	mΩ
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =-4.5V, I _D =-4A	-	60	95	mΩ
Forward Transconductance	g fs	V _{DS} =-5V,I _D =-4.1A	5.5	-	-	S
Dynamic Characteristics (Note4)	I	1	1			1
Input Capacitance	C _{lss}		-	650	-	PF
Output Capacitance	Coss	V _{DS} =-15V,V _{GS} =0V, F=1.0MHz	-	105	-	PF
Reverse Transfer Capacitance	Crss		-	65	-	PF
Switching Characteristics (Note 4)	·					
Turn-on Delay Time	t _{d(on)}		-	8.5	-	nS
Turn-on Rise Time	tr	V _{DD} =-15V,R _L =3.6Ω	-	4.5	-	nS
Turn-Off Delay Time	t _{d(off)}	V_{GS} =-10V,R _{GEN} =3Ω	-	26	-	nS
Turn-Off Fall Time	tf		-	12.5	-	nS
Total Gate Charge	Qg		-	12.5	-	nC
Gate-Source Charge	Q _{gs}	V _{DS} =-15V,I _D =-4A,V _{GS} =-10V	-	2.8	-	nC
Gate-Drain Charge	Q _{gd}		-	2.7	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =-4.1A	-	-	-1.2	V

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.

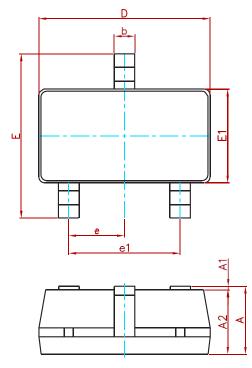
2. Surface Mounted on FR4 Board, $t \le 10$ sec.

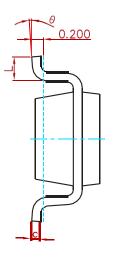
3. Pulse Test: Pulse Width \leq 300µs, Duty Cycle \leq 2%.

4. Guaranteed by design, not subject to production



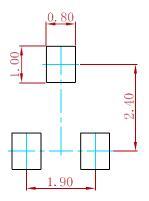
PACKAGE MECHANICAL DATA





Symbol	Dimensions I	n Millimeters	Dimension	Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.		
A	1.050	1.250	0.041	0.049		
A1	0.000	0.100	0.000	0.004		
A2	1.050	1.150	0.041	0.045		
b	0.300	0.500	0.012	0.020		
С	0.100	0.200	0.004	0.008		
D	2.820	3.020	0.111	0.119		
E1	1.500	1.700	0.059	0.067		
E	2.650	2.950	0.104	0.116		
е	0.950(BSC)	0.037	(BSC)		
e1	e1 1.800		0.071	0.079		
L	0.300	0.600	0.012	0.024		
0	0°	8°	0°	8°		

Suggested Pad Layout



Note:

Controlling dimension:in millimeters.
General tolerance:± 0.05mm.
The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
WPM3407-MS	SOT-23	3000

WPM3407-MS HF Semiconductor Compiance



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